

# SSC8041GS1

#### **P-Channel Enhancement Mode MOSFET**

#### Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	l <sub>D</sub>
-40V	±20V	11mΩ@-10V	-29A
		18mΩ@-4.5V	-23/

# > Description

This SSC8041GS1 uses advanced trench technology to provide excellent RDSON and low gate charge. The complementary MOSFETS may be used to form a level shifted high side switch, and for a host of other applications.

#### 100% UIS + ΔVDS + Rg Tested!

# Applications

- Load Switch
- PWM Application
- Power Management

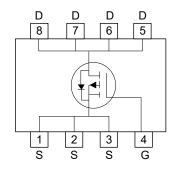
## > Ordering Information

Device	Package	Shipping	
SSC8041GS1	SOP-8	4000/Reel	

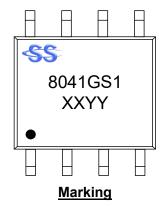
# Pin configuration



SOP-8 (Top View)



**Pin Configuration** 



(XXYY: Internal Traceability Code)



# ➤ Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit		
$V_{DSS}$	Drain-to-Source Voltage		-40	V	
V <sub>GSS</sub>	Gate-to-Source Voltage		±20	V	
	Continuous Drain Current <sup>d</sup>	T <sub>C</sub> =25℃	-29	Δ.	
l <sub>D</sub>		T <sub>C</sub> =100°C	-15	Α	
	Continuous Drain Current <sup>a</sup>	T <sub>A</sub> =25℃	-13	Δ.	
IDSM		T <sub>A</sub> =70°C	-9.8	A	
I <sub>DM</sub>	Pulsed Drain Current <sup>b</sup>		-80	Α	
Б	Power Dissipation <sup>c</sup>	Tc=25°C	14	14/	
P <sub>D</sub>		T <sub>C</sub> =100°C	5.6	W	
Б	Power Dissipation <sup>a</sup>	T <sub>A</sub> =25°C	3.1	10/	
P <sub>DSM</sub>		T <sub>A</sub> =70°C	2	W	
las	Avalanche Current <sup>b</sup> L=0.5mH Single Pulse		-15	Α	
Eas	Avalanche Energy <sup>b</sup> L=0.5mH Single Pulse		56.25	mJ	
TJ	Operation junction temperature		-55~150	°C	
T <sub>STG</sub>	Storage temperature range		-55~150		

# ➤ Thermal Resistance Ratings (T<sub>A</sub>=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	40	°C/W
$R_{ heta JC}$	Junction-to-Case Thermal Resistance	8.9	°C/W

#### Note:

- a. The value of R<sub>θJA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with T<sub>A</sub>=25 °C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P<sub>D</sub> is based on T<sub>J(MAX)</sub>=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

SSC-V1.2 www.sscsemi.com Analog Future



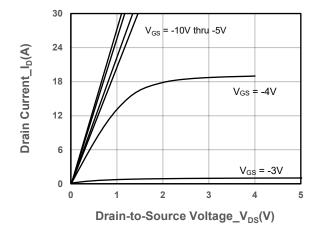


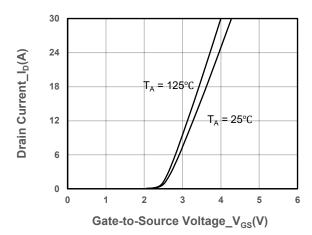
# $\succ$ Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = -250uA$	-1.2	-2.2	-3	V
	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -15A		11	14	- mΩ
Drain-Source On-Resistance		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A		18	23	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	Igss	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±100	nA
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -5A		-0.7	-1.3	V
Gate Resistance	R <sub>G</sub>	V <sub>DS</sub> = 0V, f = 1MHz		8		Ω
Input Capacitance	Ciss	\\ - 00\\\\ - 0\\		2650		
Output Capacitance	Coss	$V_{DS} = -20V, V_{GS} = 0V,$ f = 1MHz		240		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>	- I = IMH2		220		
Total Gate Charge	Q <sub>G</sub>	10)/ )/ 00)/		35		nC
Gate to Source Charge	Q <sub>GS</sub>	$V_{GS} = -10V, V_{DS} = -20V,$		6		
Gate to Drain Charge	Q <sub>GD</sub>	- I <sub>D</sub> = -10A		12		
Turn-on Delay Time	T <sub>D(ON)</sub>			12		
Rise Time	Tr	V <sub>GS</sub> = -20V, V <sub>DS</sub> = -10V,		40		
Turn-off Delay Time	T <sub>D(OFF)</sub>	$R_L = 2\Omega$ , $R_G = 6\Omega$		50		ns
Fall Time	T <sub>f</sub>			20		
Diode Recovery Time	Trr	I <sub>F</sub> =-20A, di/dt=500A/us		20		ns
Diode Recovery Charge	Qrr	I <sub>F</sub> =-20A, di/dt=500A/us		18		nC

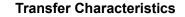


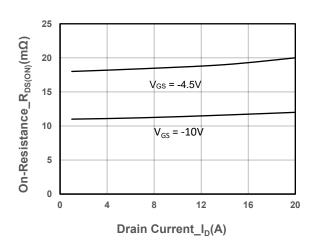
## > Typical Performance Characteristics (T<sub>A</sub>=25℃ unless otherwise noted)

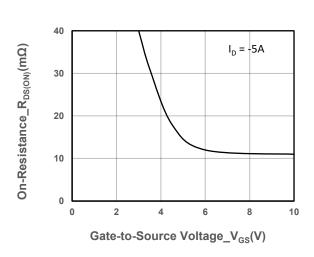




#### **Output Characteristics**

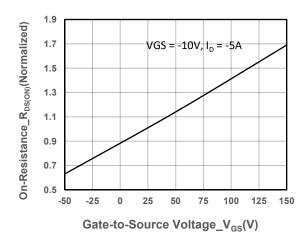


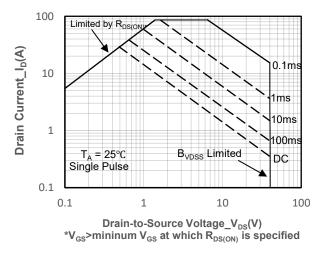




#### On-Resistance vs. Drain Current and Gate Voltag

On-Resistance vs. Gate-to-Source Voltage



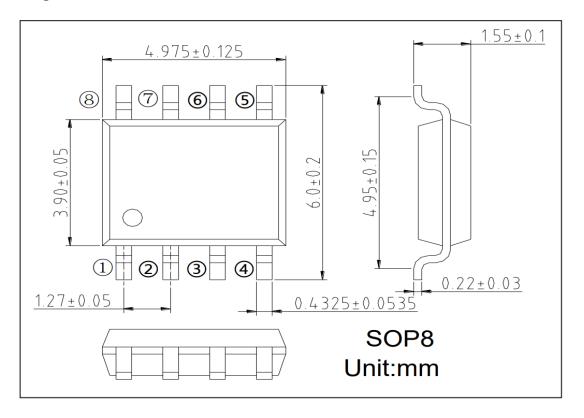


On-Resistance vs. Junction Temperature

Safe Operating Area vs. Junction-to-Ambient



# Package Information



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